PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hideto MONZEN	12/22/2009
Hiroyuki HASHIMOTO	12/22/2009
Takuya FUJIKAWA	12/22/2009
Hiroshi HAYASHI	12/22/2009
Tsuneo IMATANI	12/22/2009

RECEIVING PARTY DATA

Name:	Toyo Seikan Kaisha, Ltd.
Street Address:	3-1, Uchisaiwai-cho 1-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-8522

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12670414

OP $40.00 12670414

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	P37889
NAME OF SUBMITTER:	Stephen M. Roylance

Total Attachments: 1
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Assignment

In consideration of One Dollar ($1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned, Hideto MONZEN, Hiroyuki HASHIMOTO, Takuya FUJIKAWA, Hiroshi HAYASHI and Tsuneo IMATANI, all citizens of Japan, residing respectively at Kanagawa, Japan, Kanagawa, Japan, Kanagawa, Japan, Saitama, Japan and Kanagawa, Japan.

Hereby sell, assign and transfer to Toyo Seikan Kaisha, Ltd. a corporation of Japan having a place of business at 3-1, Uchisaiwai-cho 1-chome, Chiyoda-ku, Tokyo 100-8522, Japan its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith December 22, 2009, and is entitled Apparatus for Feeding Molten Resin, and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: December 22, 2009

Hideto Monzen (L.S.)
Hiroyuki Hashimoto (L.S.)
Takuya Fujikawa (L.S.)
Hiroshi Hayashi (L.S.)
Tsuneo Imatani (L.S.)
(L.S.)

Witness